

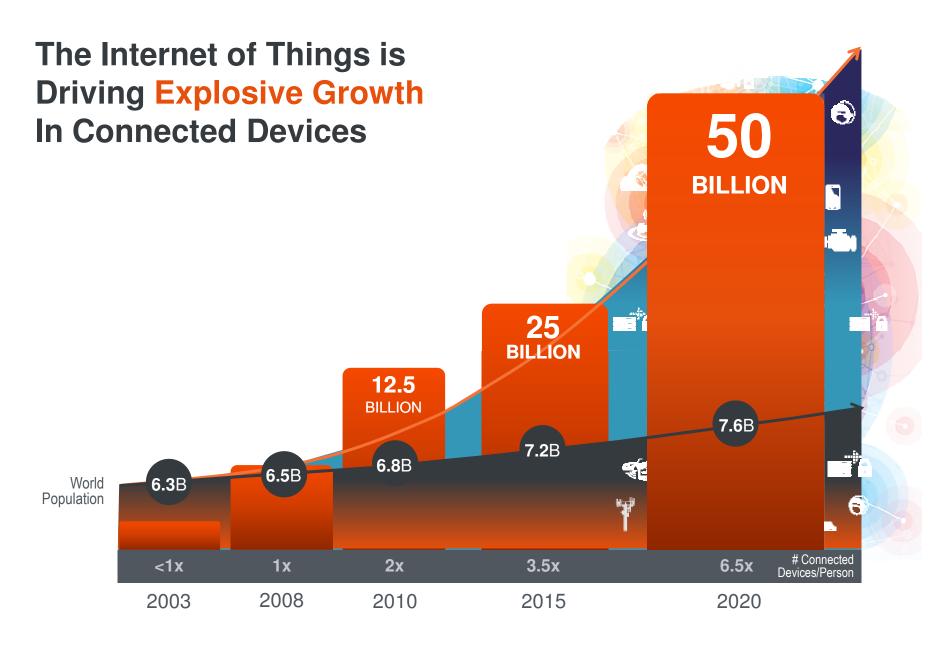
Create a Wearable Device with a Hybrid Architecture WaRPboard.org

KT Ahn | Business Development Manager July. 2014





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What Is A Wearable Device?

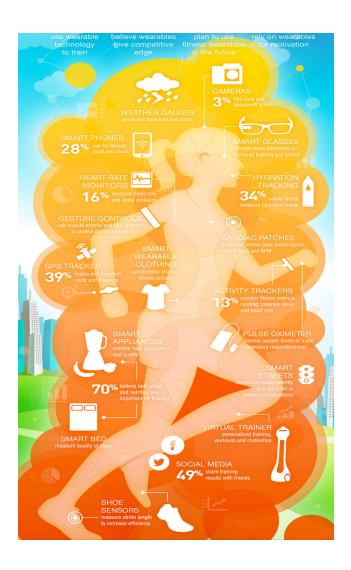
 Products that enhance the user's experience as a result of the product being worn through sensing, connectivity and processing of data

Key Technology Market Trends for Wearables:

- Miniaturization
- Low power
- Connectivity
- Multiple sensors



Austin Marathon – Freescale Survey



- 74% use wearables to train
- 88% of people surveyed said they rely on wearables for motivation similar to a coach
- 78% believe wearables give them a competitive edge
- 88% plan to use fitness wearables in the future



Smart Device Market Trend

Smart phone growth Trend

Smart device market forecast

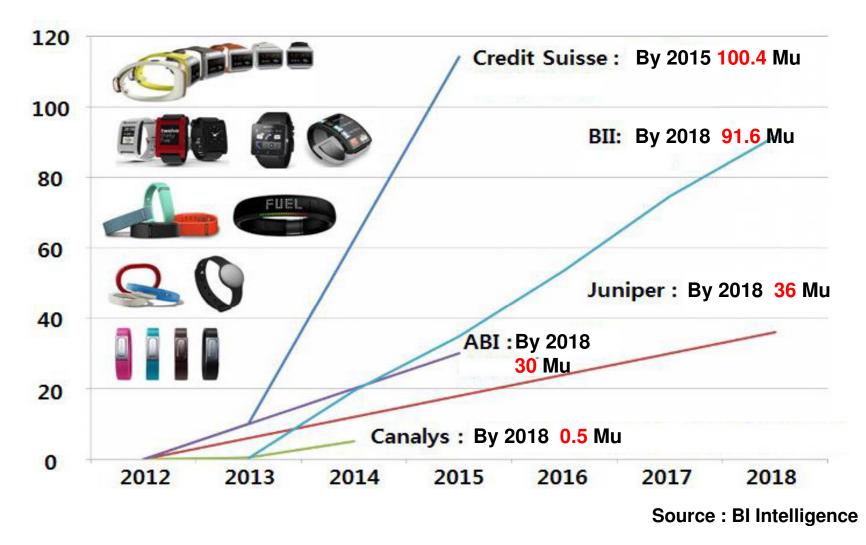


Source : Flurry Analytic & KT E&M Research

Source : Ericsson Mobility



Smart Watch Unit Forecast by Researchs



•Smart Watch would be the most fast growing wearable device in near future



Wearable Market: Segmentation

Vertical	Categories
Fitness & Wellness	Sports & Heart Rate Monitors Pedometers, Activity Monitors Smart Sport Glasses Smart Clothing Sleep Monitors Emotional Measurements
Healthcare & Medical	CGM (Continuous Glucose Monitoring) ECG Monitoring Pulse Oximetry Blood Pressure Monitors Drug Delivery (Insulin Pumps) Wearable Patches (ECG, HRM, SpO2)
Infotainment	Smart Watches Augmented Reality Headsets Smart Glasses Wearable Imaging Devices
Industrial & Military	Hand-worn Terminals Augmented Reality Headsets Smart Clothing



Wearable Market: Diverse Usage Models





Wearable's Challenge

"Stickiness" of the wearable device: Must drive long-term engagement and impact behavior



Space



Power Consumption & Charging

Usability









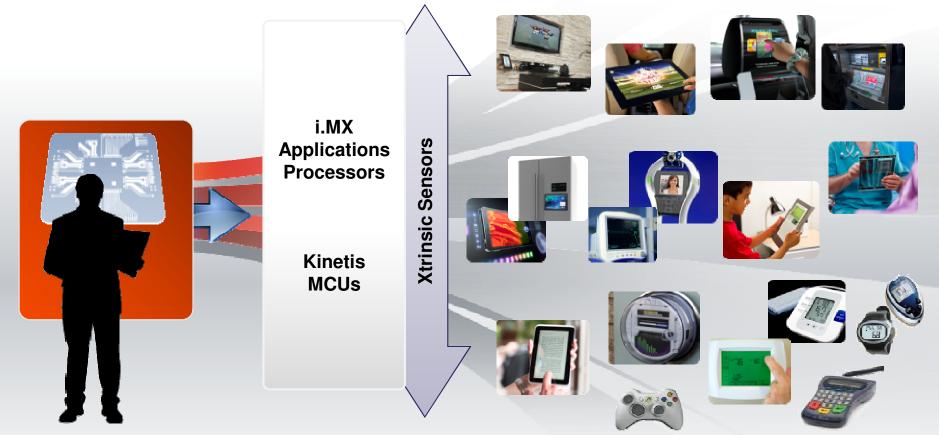
WaRP – WearAble Reference Platform







Freescale: Broadest Portfolio to Support IoT Applications



Freescale serves more markets than any other supplier

- Broadest portfolio of ARM-based products in the industry
- World-class scalability and flexibility within product portfolios
- Products aligned with development needs for Internet of Things (IoT)
- Supported by Freescale Sensors



Creating Wearable Innovation



Key development challenges	 Form factor, battery life, cost and usability
Ecosystem	Over 15 partners
Scalable	 Modular architecture to enable rapid platform evolution
Open Source	 Community drives innovation
Freescale External Use 11	REvolution Robotics

WaRP Architecture



	Wearable Reference Platform
Small Form Factor	• Main board 38 x14 mm
	Kov components selected for power memt capabilities
Battery Life	 Key components selected for power mgmt capabilities Hybrid Architecture: ARM® Cortex®A9 main compute engine and Cortex-M0+ sensor hub Wireless Charging
Usability	 Hybrid architecture to allow improved user experience Flexibility: LCD & E-Ink displays, Wi-Fi & BT 4.0 module Android 4.3 for ease of development
Cost	 \$149 sales price for the WaRP kit Low cost BOM Open Source Hardware & Software: BOM and design files available
Expectics Doers for Innovation	WaRPboard.org
	Revolution Robotics

Wearable Reference Platform

 Speeds and eases development for creating wearable devices by addressing key technology challenges which frees developers to focus on creating differentiated features





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Bill of Materials – Open Source



for

Comment	Description	Designator	LibRef	Qty	Value	Footprint	Part No.
2450AT07A0100	Johanson Technology Inc 1mm x 0.5mm 2.4GHz Ultra Mini Chip Antenna	ANTI	2450AT07A0100	1		2450AT07A0100	2450AT07A0100
Coax RF		ANT2	Coax RF	1		W.FL-R-SMT-1	W.FL-R-SMT-1
Header 2	Header, 2-Pin	ВАТ	Header 2	1		Small Solder Pads	
CapacitorSM	Capacitor	C1, C4, C7, C11, C15, C56, C61, C75, C76, C77, C81	CapacitorSM	11	22uF	0603 (1608) Cap High Density	GRM188C80G226MEA0 D
CanacitorSM	Canacitor	C2 C8 C9 C13 C18 C20	CanacitorSM	22	4 7uF	0402 (1005) Can High Density	C1005X5R01475M050BC

A full bill of materials will be provided on <u>WaRPboard.org</u> product development

capacitorsin	Capacitor	C3, C3, C0, C10, C12, C14,	Capacitorsin	110	0.2201	0201 (0000) Cap High Density	C0003/3/0722-1003000
		C16, C17, C19, C22, C23,					
		C25, C26, C28, C29, C30,					
		C31, C37					
Capacitor	Capacitor	C34, C35, C119, C120	Capacitor	4	8pF	0201 (0603) Cap High Density	C0603C0G1E080D030BA
CapacitorSM	Capacitor	C38, C39, C40, C41, C44,	CapacitorSM	31	0.1uF	0201 (0603) Cap High Density	GRM033R60J104ME19D
		C46, C47, C48, C52, C53,					
		C54, C57, C58, C59, C62,					
		C63, C64, C65, C68, C70,					
		C91, C94, C95, C109, C110,	,				
		C111, C113, C114, C116,					
		C121, C134					
CapacitorSM	Capacitor	C42, C55, C60, C66, C67,	CapacitorSM	7	0.01uF	0201 (0603) Cap High Density	GRM033R70J103KA01D
		C69, C71					
CapacitorSM	Capacitor	C50, C51, C79	CapacitorSM	3	4.7uF	0603 (1608) Cap High Density	GRM188R60J475ME19D
CapacitorSM	Capacitor	C74, C82, C84, C85, C87,	CapacitorSM	15	1uF	0201 (0603) Cap High Density	C0603X5R0J105M030BC
	-	C88, C93, C106, C107,					
		C123, C124, C126, C127,					
		C131, C132					
CapacitorSM	Capacitor	C78, C80, C86, C122, C133	CapacitorSM	5	2.2uF	0402 (1005) Cap High Density	LMK105BJ225MV-F
CapacitorSM	Capacitor	C83, C96, C98, C102, C104,	CapacitorSM	6	1uF	0402 (1005) Cap High Density	C1005X5R1V105M050BC
		C125	.				



Reference Design Comparison for Wearable projects









Raspberry Pi	Arduino	Beagle Bone Black	ToQ	WaRP
No Wi-Fi or BT			Yes – Smart Watch	
DC power	DC or Battery	DC Power or USB	Mirasol Display	
Arduino compatible			None	
\$25	\$110	\$45 -\$89	\$399	\$149
	Creative Commons			
	PiNo Wi-Fi or BTDC powerArduino compatible	PiINo Wi-Fi or BTImage: ComparisorDC powerDC or BatteryArduino compatibleImage: Comparisor\$25\$110Creative	PiBiackNo Wi-Fi or BTImage: Comparing the second se	PiBlackNo Wi-Fi or BTImage: Sector of the se



Processor selection: MCUs vs Apps Processors

MCUs optimized for simple, single function solutions

MPUs provide higher performance, ability to run a full operating system and an SDK for applications development .

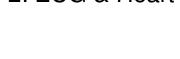
A hybrid approach addresses:

- The diversity of the wearable's market
- Optimized, scalable power management
- Small footprint

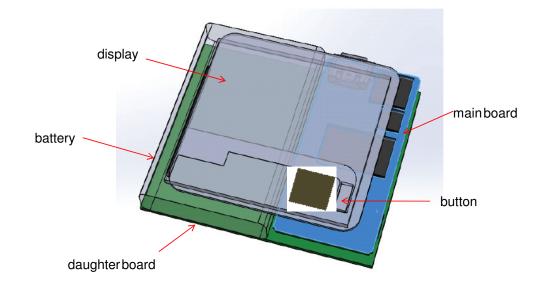


Application Examples

- Time, chrono, lap time, alarms
- · Smart music player with audio streaming to headset
- Photo gallery and video player
- Bluetooth Smart Pairing with Android Device
- Wi-Fi connectivity
- Compass
- Free fall detection
- Pedometer / activity monitor
 - Distance traveled
 - Calories
- Wake up on motion
- Charging over USB
- Wireless charging
- Phase 2: ECG & Heart Rate Monitoring









Block Diagram



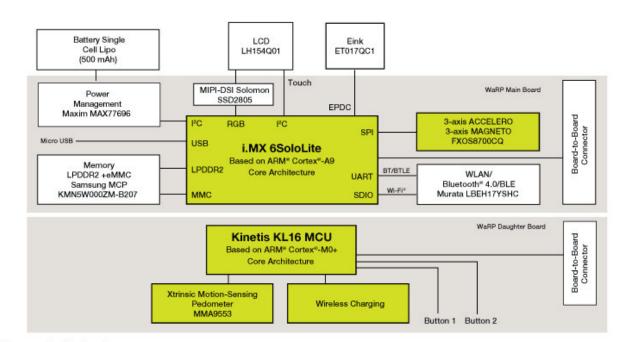
Main Board PCB size: 38 mm x 14 mm (1.49"x 0.55")





Daughter Board PCB size: 42 mm x 42 mm (1.65" x 1.65")

Wearable Reference Platform (WaRP) with Standard Daughter Board

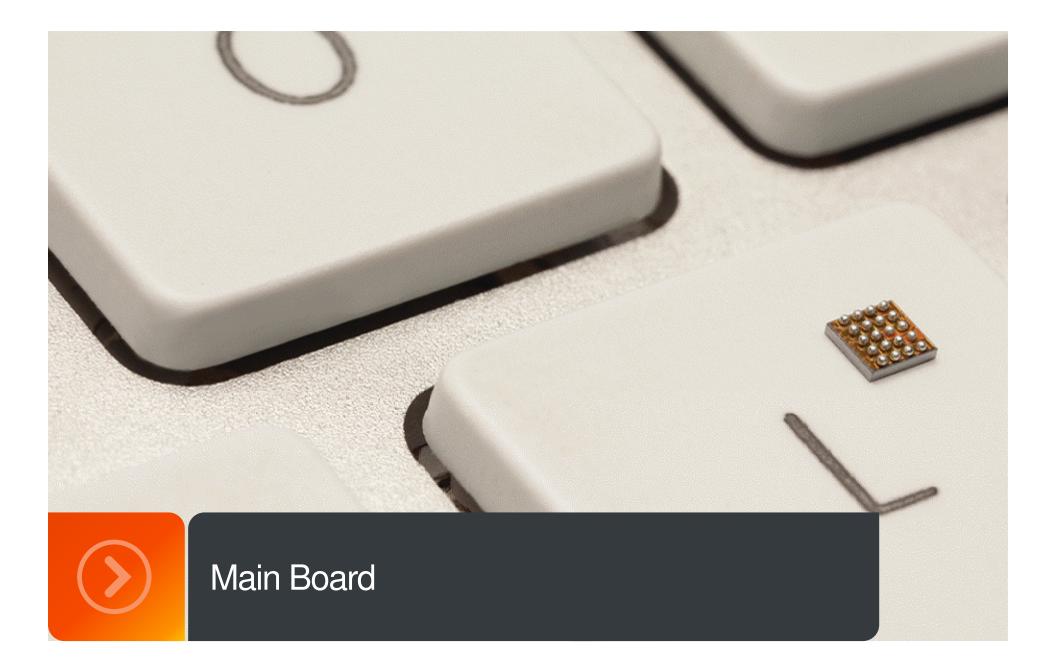


Freescale Technology

Designed to be able to productize



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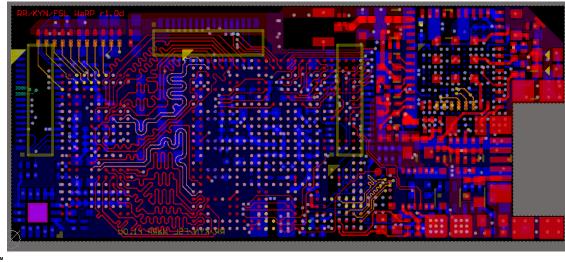




Main Board PCB Design

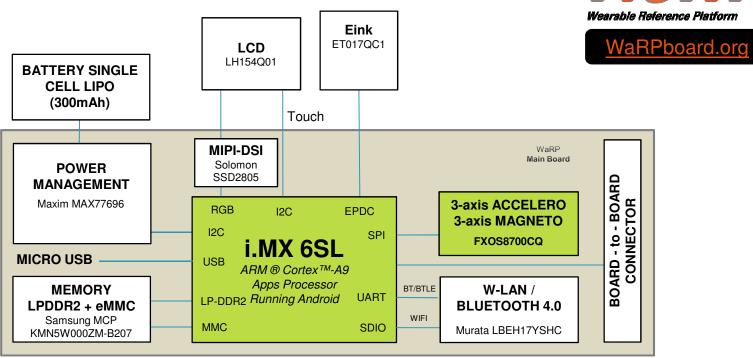


- Small form factor through tight design
 - The hard work of integrating hardware into small form factor is done by WaRP so you can focus resources on the application.
- Main Board PCB Specifics
 - 16 x 38mm footprint for main board which includes all critical functions.
 - 10 layers
 - Blind/Buried vias using HDI (high density interconnect) PCBs same/similar tech used in mobile phones.





Main Board





Main Board PCB size: 38 mm x 14 mm (1.49"x 0.55")

WaHP



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WaRP Main Board Components



Component	Use Case	Reason Selected
Freescale MCIMX6L7DVN10AB	Main compute engine – connectivity, data processing, user interface. Runs Android.	Small footprint (13x13mm), eInk display support, low power apps processor
Murata LBEH17YSHC Wireless Module	Wi-Fi (802.11 b/g/n) – connect to cloud Bluetooth (-1000 m) – tether to smartphone/tablet	Small form factor (7x7mm) single module. market tested (cell phones), low power
Samsung MCP KMN5W000ZM-B207	LP-DDR2 – low power system memory 4GB eMMC for storage	Small tightly coupled design, saves up to 40% board space, consumes less energy
Eink EPD (ET017QC1) and LCD (LH154Q01) display options	Graphic User Interface - options for both interactive highly visual displays (LCD) to constant always-on notification displays using monochrome e-ink	E-Ink panel - lowest power display technology, LCD panel – most broadly used 1.5" high density display with touch in wearables
Maxim MAX77696 PMIC	System Power Management IC	Regulators from 2.6V to 5.5V Dual Input Battery Charger Supports both E-Ink and LCD displays
Xtrinsic FXOS8700CQ 6DOF eCompass Sensor	Direction awareness & Motion detection – included on main board to allow it to be a standalone wearable compute platform	Low noise, low offset 3-axis accelerometer + magnetometer eCompass sensor enabling <5 ^o absolute heading accuracy and ±0.1 ^o resolution performance
Single cell lipo battery	Power source	Provides highest energy density





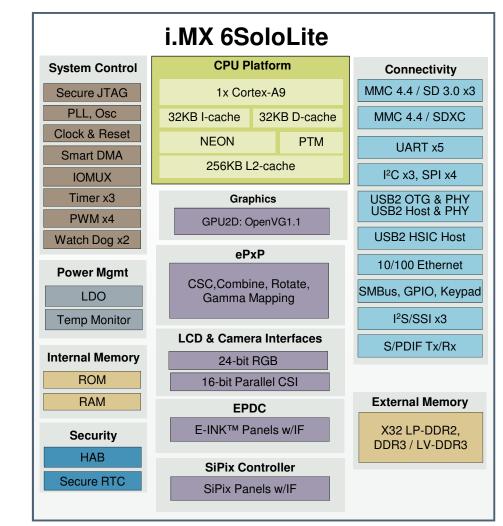
i.MX 6SoloLite Multimedia Processor

Specifications

- CPU: 1x ARM® Cortex®-A9 @ 1GHz
- Core Voltage: 1.1V
- Package: 0.5mm 13x13 MAPBGA

WaRP Use Case

- Lower active & stand by power via:
- Clock/power gating
- Dynamic voltage & frequency scaling
- x32 LP-DDR2 & managed NAND
- EPD /LCD Controller & 2D GPU
- USB OTG 2.0 for charging and for updates to the end device
- Interfaces: UART for BT, SDIO for Wi-Fi, SPI for the accelerometer



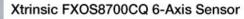


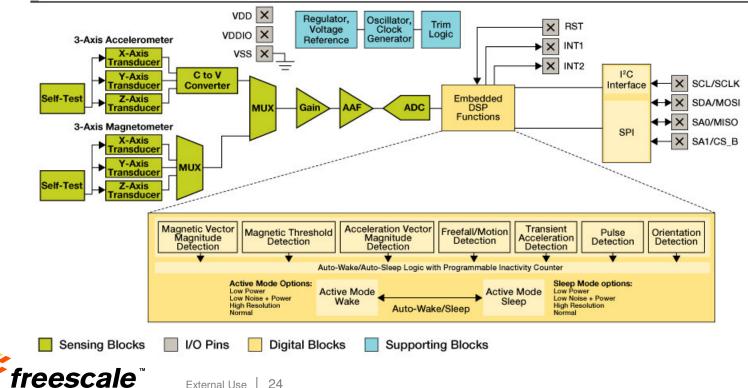
Xtrinsic FXOS8700CQ 6DOF eCompass Sensor

Low noise, low offset 3-axis accelerometer + magnetometer eCompass sensor enabling <5° absolute heading accuracy and ±0.1° resolution performance

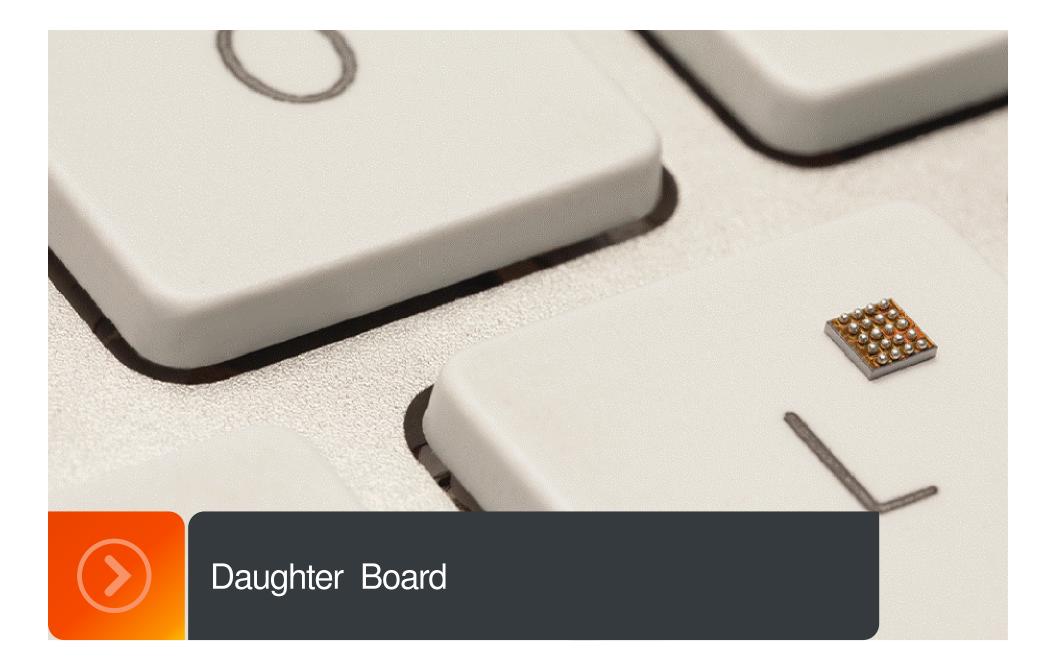
Differentiating Points

- 14b data gcell ADC with 33% lower noise and 3x lower offset
- 16b data mcell ADC with 0.6 uT-rms noise density
- Vector magnitude change detection for faster system response and lower power
- Autonomous hard iron calibration
- Production-ready calibration and award winning eCompass software
- Pin compatible with Freescale accelerometer portfolio







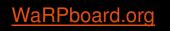




Daughtercard PCB Design

- Optimized for low cost
- Daughtercard PCB Specifics
 - 42 mm x 42 mm footprint
 - 2 layer board
 - No blind vias
 - Easy to manufacture



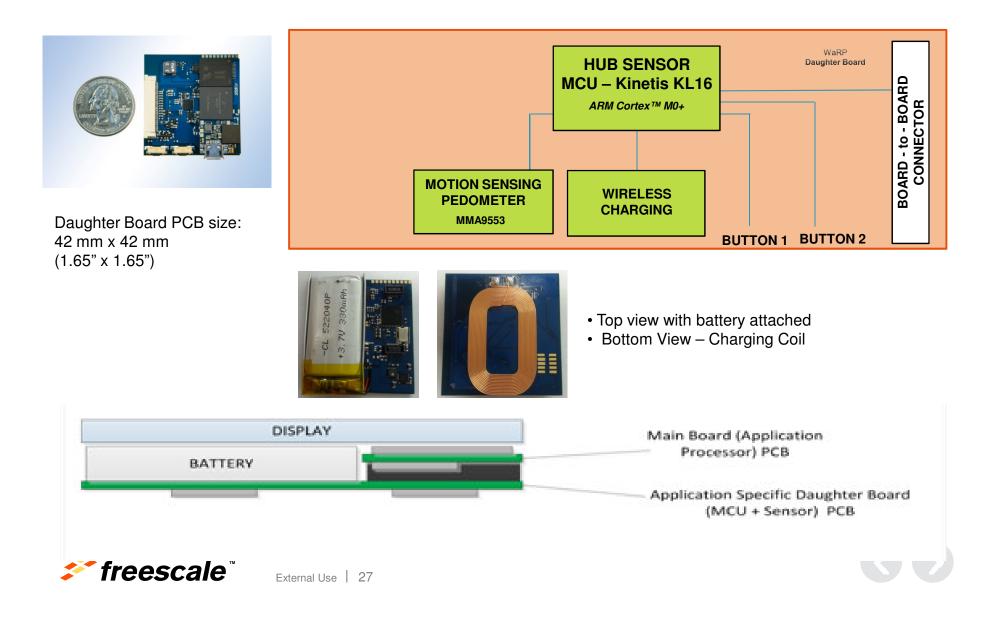








WaRPboard.org



Daughter Card Components

Component	Use Case	Reason Selected
Kinetis KL16 - MKL16Z128VFT4	Sensor Hub, system power and application manager to maximize battery life and hosts wireless charging.	Always active so needed low power MCU. Scalability to add or change function of daughtercard
Xtrinsic MMA955xL 3-Axis Accelerometer	Pedometer features	Intelligent Motion Platform with embedded libraries for pedometer.
S-Axis Acceleronieler		Power management features and low power modes
Vishay 5W Charging Coil	Charging	Supports Chi standard, small size and is broadly available
Wireless Charging Software	Innovative charging technologies are critical to the adoption of wearables	Chi compliant wireless charging embedded software for 5Watts – configurable





Kinetis L Series: Low Power Pillars

Ultra-efficient Cortex-M0+ processor

 Most energy-efficient 32-bit processor on the market with industry leading throughput/mA

Energy-saving architecture

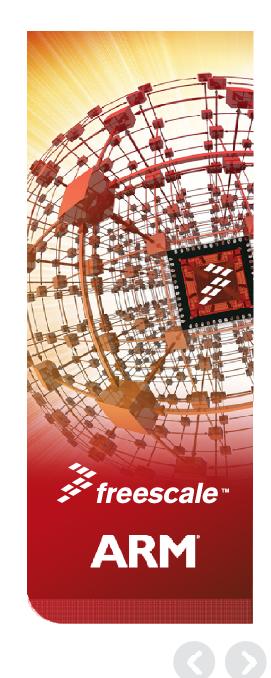
 Optimized for low power with 90nm TFS technology, clock and power gating techniques, and highly efficient platform featuring a low power boot option, bit manipulation engine, peripheral bridge crossbar and zero wait state flash memory controller

Ultra-low power modes

 Several, flexible power modes fit for different application use cases designed to maximize battery life

Energy-saving peripherals

 Smart peripherals with functionality in deep sleep modes can make intelligent decisions and process data without waking up the core





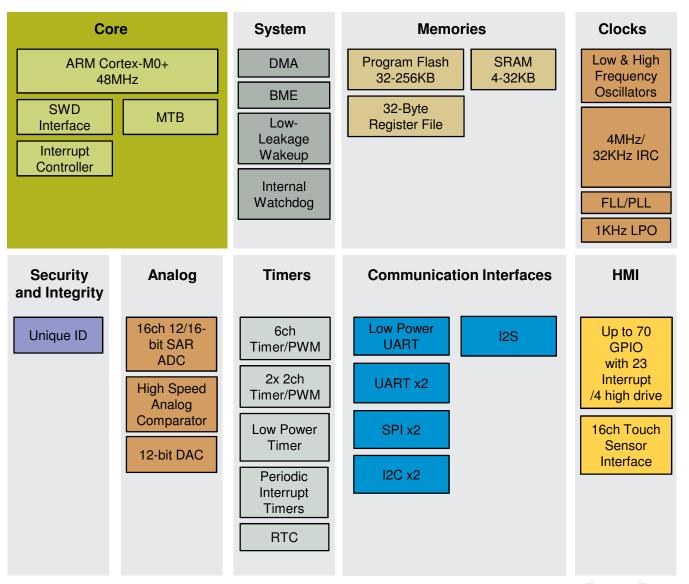
Kinetis L Series MCUs: KL16 Block Diagram

Specifications

- CPU: 1x ARM Cortex-M0+ @ 48MHz
- 32QFN 5x5x1/0.5mm

WaRP Use Case

- UART for communication to the main board
- PWM for buzzer (notifications)
- I2C to motion detector sensor
- SPI to E-Ink display for power management
- GPIO for buttons





Xtrinsic MMA955xL Variations

MMA9550L Block Diagram

• MMA9550L

- Infrastructure only functions
- User Flash: 6.5 Kbytes
- User RAM: 576 bytes

• MMA9551L

- Infrastructure plus gestures
- User Flash: 4.5 Kbytes
- User RAM: 452 bytes

• MMA9553L

- Infrastructure plus pedometer
- User Flash: 1.5 Kbytes
- User RAM: 200 bytes

• MMA9559L

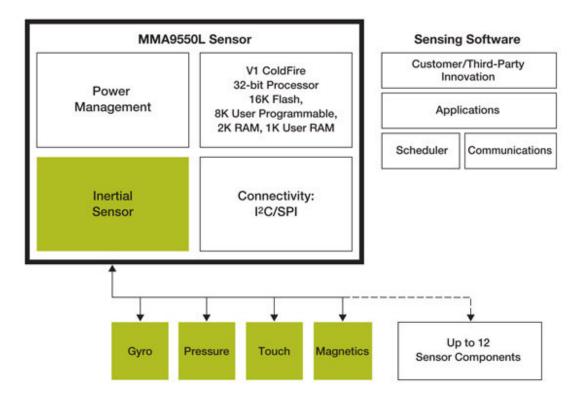
- Lightweight Infrastructure
- User Flash: 14 Kbytes
- User RAM: 1.5 bytes

Software

- Full enablement suite of tools including Freescale CodeWarrior
- · Project Wizard creates project in as few as nine clicks
- CodeWarrior optimizing C/C ++ compilers for ColdFire included
- · Integrated support for hardware background debugger

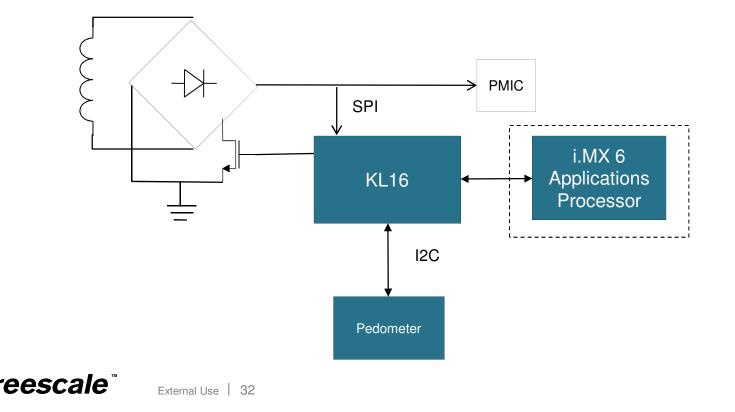


External Use 31



Wireless Charging Receiver

- Uses the latest industry standard Chi standard
- Charge without the bulky micro-USB connector to create a true connector-less device and minimize form factor
- Implements a discrete topology to offer ultimate flexibility over ASIC solution
- Uses commercially available components no special components required
- Provides ease of implementation with software provided in library format

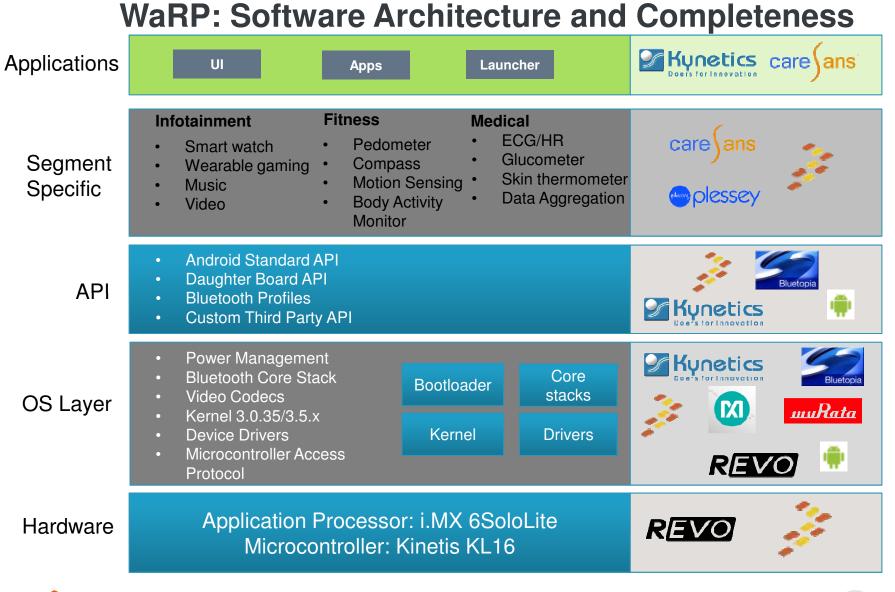














What is Android?



Connectivity	LTE to NFC On-demand and autonomously
Context Awareness	System capable of higher-level concepts, functions, and behaviors
Interactive and Intelligent	Learn behaviors based on user's response. Natural user interface: Spoken, gestures.
Extensible	Application Framework capable of performing a combinatorial set of tasks



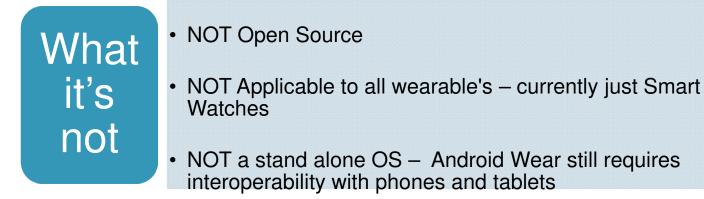
WaRP Android Software Implementation



Connected	Fully connected stack accessible via Java SDK Flexible recovery system for OS updates
Extensible	Large developer community can leverage full standard Android SDK & standard dev tools Open platform – two BSP versions, full open source & advanced optimized via click through license
Interactive & Intelligent	Android is only OS with an optimized & lightweight surface renderer & advanced touch human interface
Context Awareness	Extension of SDK used simple messaging system to interface with daughter card & access data from sensors
	ernal Use 36

Android Wear – What's The Impact

	 The released SDK includes API libraries & dev tools to build, test & debug apps for devices running Android Wear.
What it is	 Similar to the GDK for Google Glass – The Glass OS can be installed only on Google Glass and is solely owned by Google
	 Google have not released the source code therefore cannot be ported to the WaRP board or any third party platform at this time.





Launch & Community







Community

WaRPboard.org



WaRPbo support f software licensing

WaRPbo wearable with the a architect 6SoloLite

- WaRP community can help you tackle challenges, develop quickly and innovate!
- Includes main board, sensor hub daughtercard, LCD display, battery and mini-USB cable
- Target MSRP \$149

KL16 MCU, is implemented on the daugntercard, which is used as a sensor hub as well as a wireless charging MCU.



Community driven by CIrcuitco

Technical Features



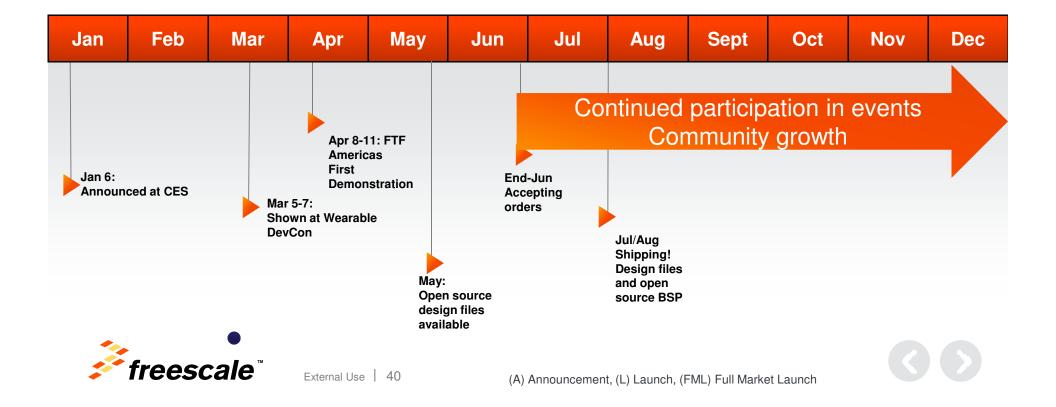


WaRP Timeline Calendar

- Available Now
 - WaRPboard.org Website
 - Block Diagram
 - WaRPboard Google Group



- WaRPboard.org
- Distributors Arrow and Avnet



Wearables Summary





Versatile Applications

More than just smart watches! The possibilities are endless.



Scalable, Modular and Open Source

WaRP is a scalable, modular, and open source reference platform provided by Freecale, Kynetics, Revolution Robotics and Circuitco that will evolve with market and enable innovation.



Productizable

Form factor board that can be productized because components are all readily available



Growth Opportunites

Growing market covering multiple vertical segments









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